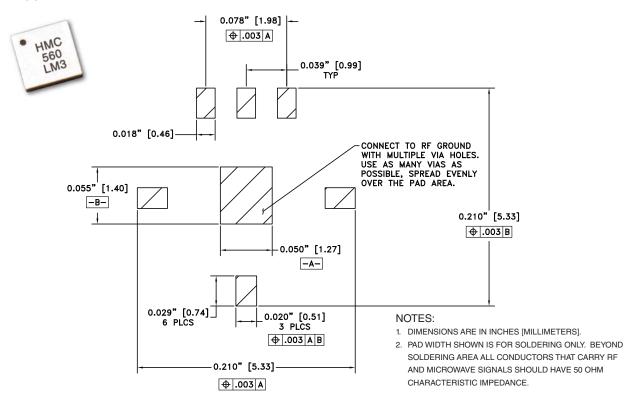


LM1 – LEADLESS CERAMIC HIGH FREQUENCY SMT PACKAGE

Suggested LM1 PCB Land Pattern 0.039" [1.00] TYP 0.018" [0.46]-HMC 331 LM1 0.029" [0.74]-CONNECT TO RF GROUND WITH MULTIPLE VIA HOLES. USE AS MANY VIAS AS POSSIBLE, SPREAD EVENLY OVER THE PAD AREA. 0.053" [1.35] 0.212" [5.38] -B-**⊕**.003 B 0.020" [0.51] 2 PLCS 0.057" [1.45]-**⊕** .003 B -A-NOTES: 0.078" [1.97] 1. DIMENSIONS ARE IN INCHES [MILLIMETERS]. 2 PAD WIDTH SHOWN IS FOR SOLDERING ONLY BEYOND **⊕**.003 A SOLDERING AREA ALL CONDUCTORS THAT CARRY RF AND MICROWAVE SIGNALS SHOULD HAVE 50 OHM 0.208" [5.28] CHARACTERISTIC IMPEDANCE. **⊕**.003 A

Suggested LM3 PCB Land Pattern



For price, delivery, and to place orders, please contact Hittite Microwave Corporation: 20 Alpha Road, Chelmsford, MA 01824 Phone: 978-250-3343 Fax: 978-250-3373 Order On-line at www.hittite.com